

## P-Channel 40V(D-S) MOSFET

Product summary		
$V_{DS}$	-40	V
$R_{DS(ON)}$ (at $V_{GS}=-10V$ ) Typ.	11	mΩ
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ ) Typ.	15	mΩ
$I_D(T_c=25^\circ C)$	-52	A

### Features

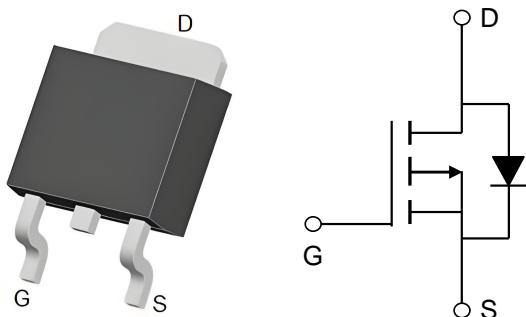
- High density cell design for low  $R_{ds(on)}$
- Trench Power LV MOSFET technology
- RoHS Compliant

### Applications

- Load Switch
- Power Management

### Pin Configuration

TO-252



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECG40P50C	TO-252	13 "	2500pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D$	Continuous Drain Current at $V_{GS}=10V$	$T_c=25^\circ C$	-52
		$T_c=70^\circ C$	-32
$I_{DM}$	Pulse Drain Current Tested	-105	A
$P_D$	Power Dissipation	$T_c=25^\circ C$	52
$E_{AS}$	Single Pulse Avalanche Energy		146 mJ
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to 150	°C

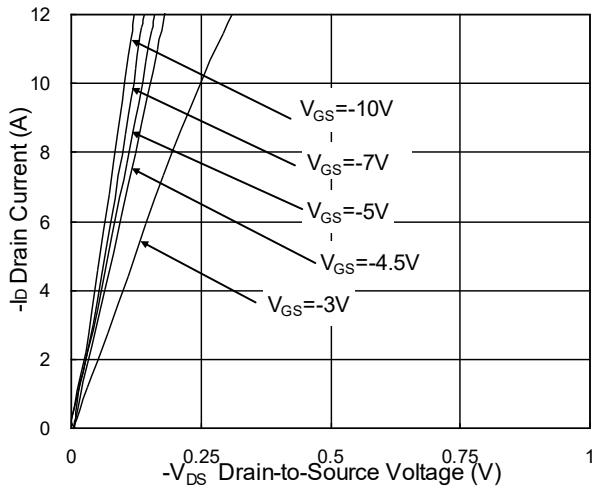
### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient	62	°C/W

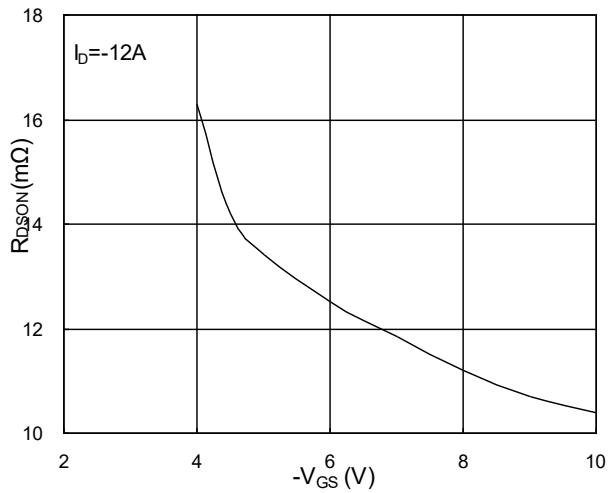
Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Static Parameters</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-32\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-18\text{A}$	--	11	13	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-12\text{A}$	--	15	20	$\text{m}\Omega$
$V_{\text{SD}}$	Forward Voltage	$I_{\text{SD}}=-1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	-1	V
<b>Dynamic Parameters</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}$ $f=1\text{MHZ}$	--	3468	--	pF
$C_{\text{oss}}$	Output Capacitance		--	317	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	235	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-12\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	--	28.6	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	7.9	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	7.6	--	nC
<b>Switching Parameters</b>						
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-1\text{A}$ $R_G=3.3\Omega$ , $V_{\text{GS}}=-10\text{V}$	--	40.5	--	nS
$t_r$	Turn-on Rise Time		--	35.6	--	nS
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	99.7	--	nS
$t_f$	Turn-off Fall Time		--	9.6	--	nS

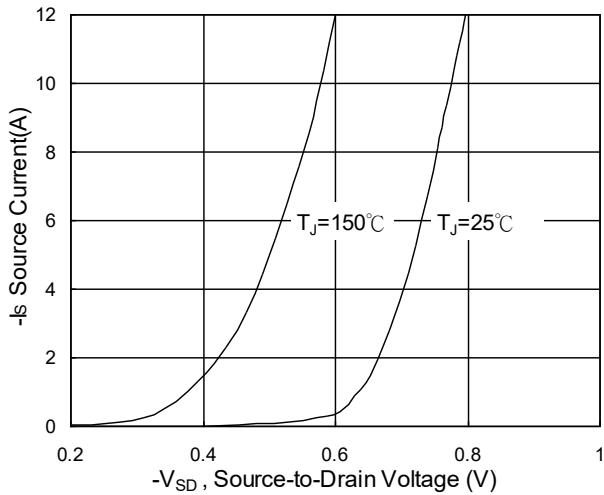
## Typical Characteristics



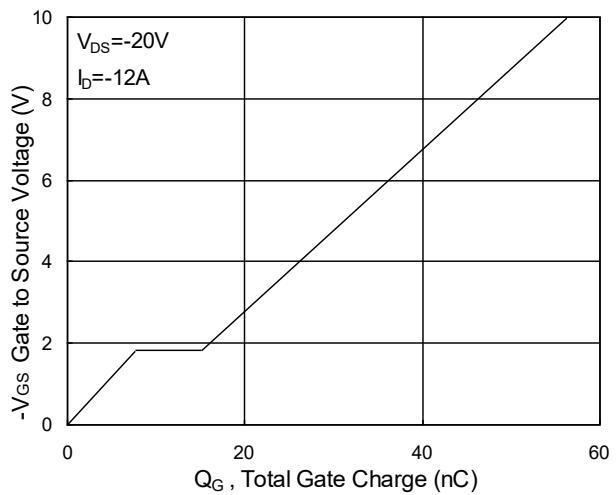
**Fig.1 Typical Output Characteristics**



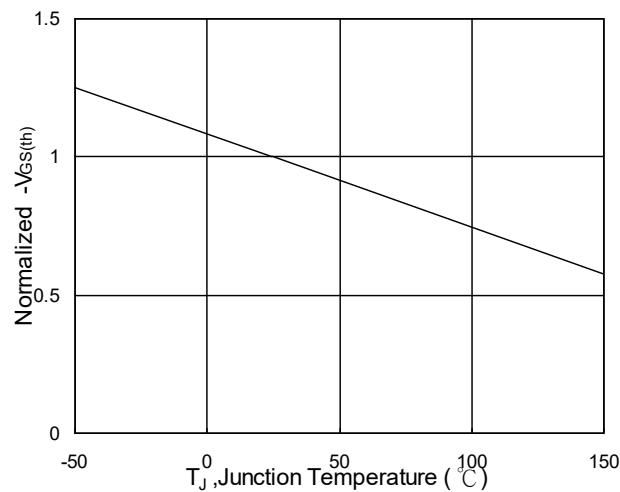
**Fig.2 On-Resistance v.s Gate-Source**



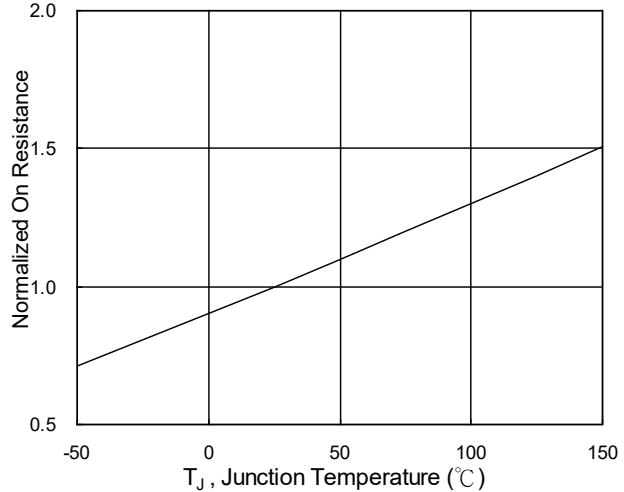
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

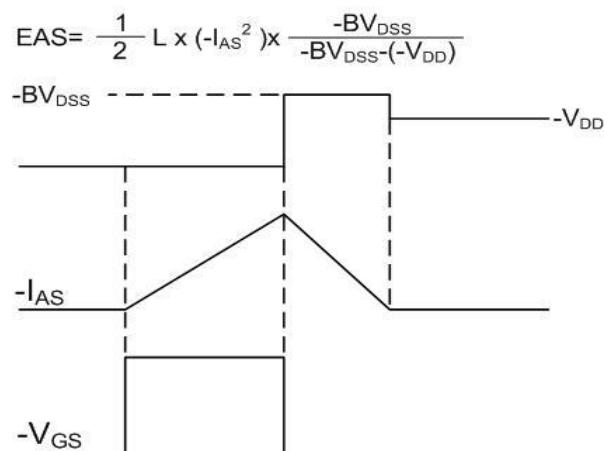
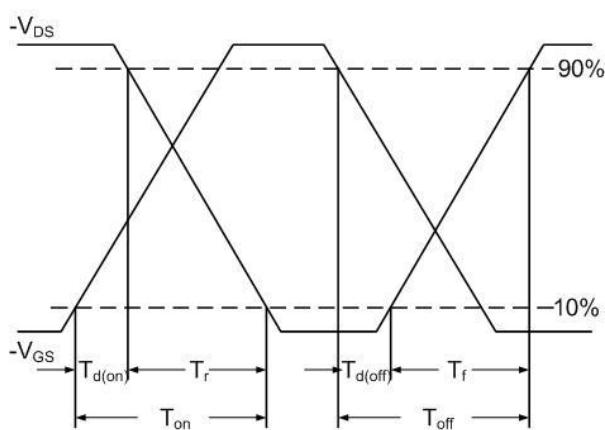
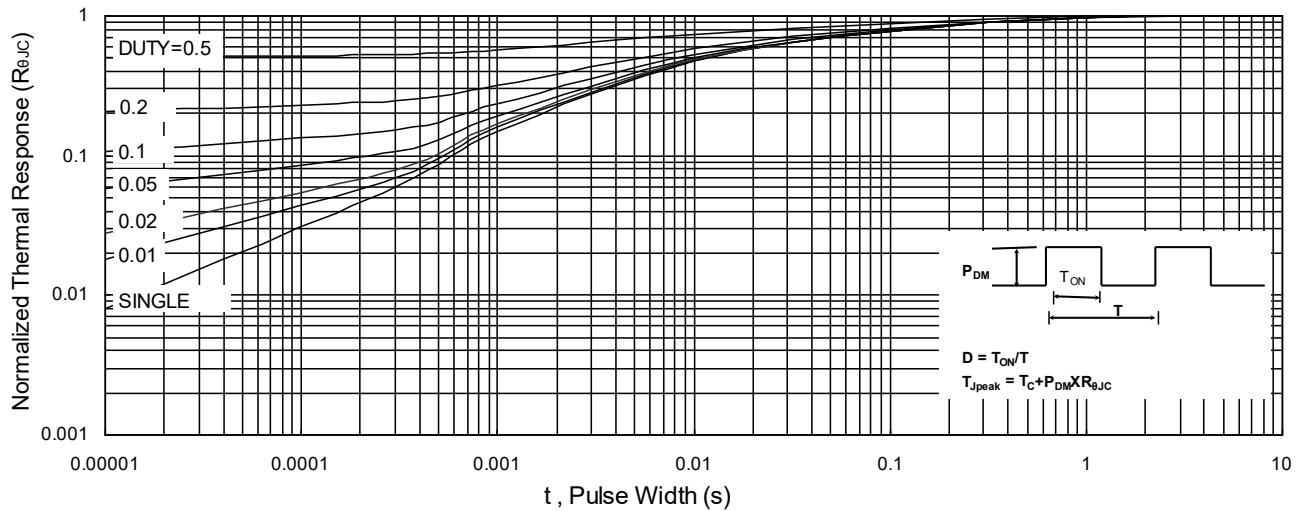
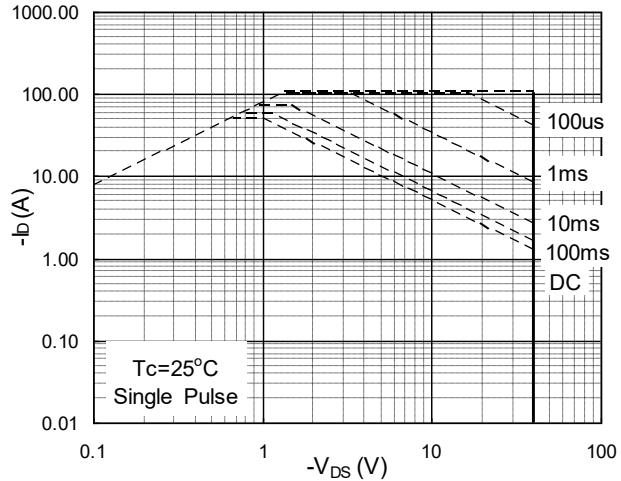
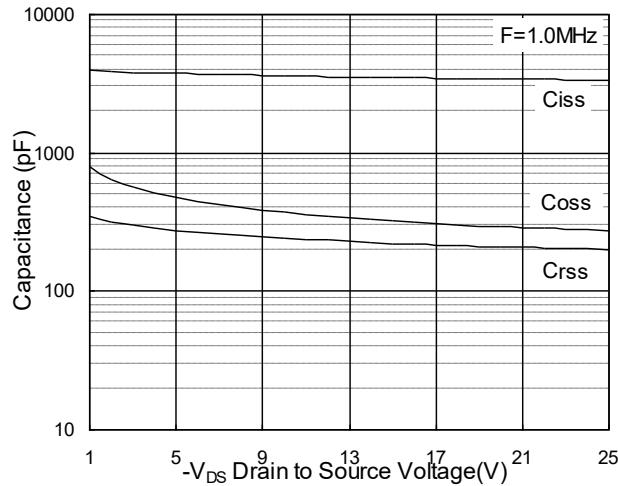


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

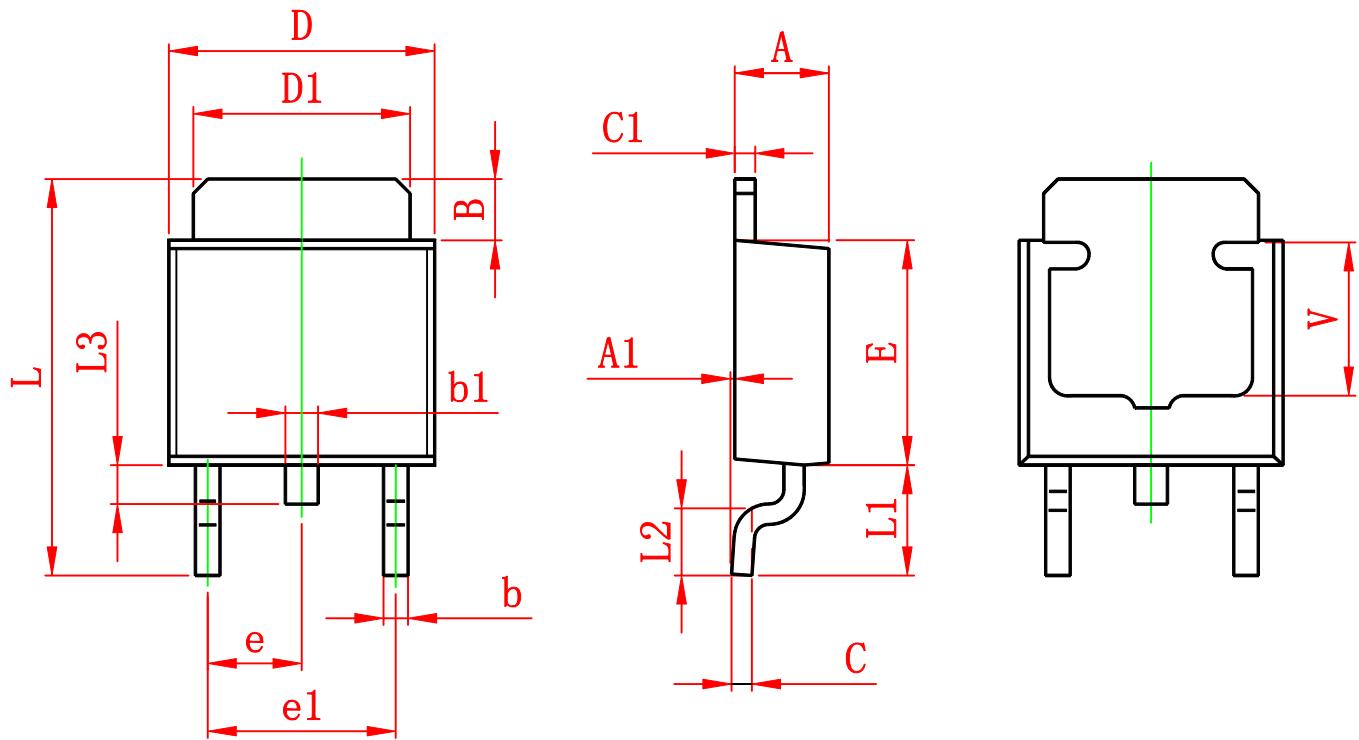


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

## Typical Characteristics



## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	